Applicant: Andreas N. Wiswesser et al.

Serial No.: 10/616,488 Filed: July 8, 2003 Page: 2 of 6 Attorney's Docket No.: 002562C2-369003

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

<u>Listing of Claims</u>:

1-21. (Cancelled)

- 22. (Previously Presented) A chemical mechanical polishing apparatus to polish a substrate, comprising:
- a platen to support a polishing pad, the platen rotatable about an axis, the platen including a plurality of optical apertures positioned at different angular positions about the axis;
 - a carrier head to hold a substrate against the polishing pad;
- a plurality of optical systems located in the platen, each of the plurality of optical systems including a light source to independently generate a light beam and direct the light beam through an associated one of the plurality of optical apertures, and a sensor to measure light from the light beam that is reflected from the substrate to generate an intensity signal; and
- a processor to receive the intensity signal from each of the plurality of optical systems and determine a polishing endpoint.
- 23. (Currently Amended) The apparatus of claim 22, wherein the plurality of optical systems include a first optical system having a first light source to generate a first light beam and a <u>first second</u> sensor to measure light from the first light beam that is reflected from the substrate to generate a first intensity signal, and a second optical system having a second light source to generate a second light beam and a second sensor to measure light from the second light beam that is reflected from the substrate to generate a second intensity.
- 24. (Original) The apparatus of claim 23, wherein the second light beam has a second effective wavelength that differs from the first effective wavelength.

Attorney's Docket No.: 002562C2-369003

Applicant: Andreas N. Wiswesser et al.

Serial No.: 10/616,488

Filed Page

: July 8, 2003 : 3 of 6

25. (Original) The apparatus of claim 24, wherein the first light beam and the second light beam have different wavelengths.

- 26. (Original) The apparatus of claim 24, wherein the first optical system is an offaxis optical system and the second optical system is a normal-axis optical system.
- 27. (Currently Amended) The apparatus of claim 2221, wherein the plurality of optical apertures are spaced evenly about the axis.
- 28. (Original) The apparatus of claim 27, wherein the platen includes exactly two optical apertures.
- 29. (Currently Amended) The apparatus of claim 2221, further comprising a polishing pad supported on the platen, the polishing pad having a plurality of windows, each of the plurality of windows aligned with an associated one of the plurality of optical apertures in the platen.
- 30. (Currently Amended) The apparatus of claim 2221, wherein at least one light beam has a wavelength of about 300-400 nm.

31-37. (Cancelled)

- 38. (Previously Presented) The apparatus of claim 23, wherein the first light beam and the second light beam have the same propagation angle.
- 39. (Previously Presented) The apparatus of claim 24, wherein the first optical system and the second optical system are off-axis optical systems.

Applicant: Andreas N. Wiswesser et al. Attorney's Docket No.: 002562C2-369003

Serial No.: 10/616,488 Filed: July 8, 2003 Page: 4 of 6

40. (Previously Presented) The apparatus of claim 23, wherein the first light beam and the second light beam have the same wavelength.

- 41. (Previously Presented) The apparatus of claim 22, wherein the second light beam has a second wavelength that differs from a first wavelength of the first light beam.
- 42. (Currently Amended) The apparatus of claim <u>2221</u>, wherein the plurality of optical apertures are about the same distance from the axis.
- 43. (Previously Presented) The apparatus of claim 27, wherein the plurality of optical apertures are about the same distance from the axis.
- 44. (Previously Presented) The apparatus of claim 22, further comprising an opaque polishing pad positioned on the platen, the polishing pad including a plurality of windows formed in the polishing layer and aligned with the plurality of optical apertures in the platen.
- 45. (Previously Presented) The apparatus of claim 44, wherein the polishing pad includes a polishing layer and a backing layer.
- 46. (Previously Presented) The apparatus of claim 44, wherein the windows include a solid light-transmitting material.
- 47. (Currently Amended) The apparatus of claim <u>2221</u>, wherein at least one light beam has a wavelength of about 600-1500 nm.